Application Number 10/779,920 Amendment dated June 20, 2006 Reply to Office Action of March 22, 2006

Amendments to the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

Listing of claims:

(Currently Amended) A method of cleaning a substrate comprising:
 applying an aqueous sulfuric acid solution diluted by deionized water onto the substrate;
 and

cleaning contaminants on the substrate in accordance with a reaction between the diluted aqueous sulfuric acid solution with the contaminants by applying a mega-sonic energy to the substrate including with the applied diluted aqueous sulfuric acid solution.

- 2. (Original) The method of claim 1, wherein the substrate includes a metal wiring or a metal thin film.
- 3. (Original) The method of claim 1, wherein the diluted aqueous sulfuric acid solution comprises the deionized water and sulfuric acid by a volume ratio of about 500: 1 to about 8,000: 1.
- 4. (Original) The method of claim 3, wherein the sulfuric acid has a concentration of about 10 ppm to about 1,000 ppm.
- 5. (Original) The method of claim 1, wherein the mega-sonic energy is generated using a power of about 5 Watts to about 15 Watts.
- 6. (Original) The method of claim 1, wherein cleaning the contaminants is performed for about 30 seconds to about 120 seconds.

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- 7. (Original) The method of claim 6, wherein cleaning the contaminants is performed at a temperature of about 20 degrees C to about 30 degrees C.
- 8. (Currently Amended) The method of claim 1, wherein cleaning the contaminants is performed using the method further comprises providing the substrate into a spin scrubber.
- 9. (Original) The method of claim 8, wherein the substrate is provided into the spin scrubber in a batch type, the diluted aqueous sulfuric solution is applied by a spray process, and the mega-sonic energy is applied through a bar facing the substrate.
- 10. (Original) The method of claim 8, wherein the substrate rotates at a speed of about 8 rpm to about 50 rpm.
- 11. (Original) The method of claim 1, further comprising rinsing the substrate using deionized water, and drying the substrate.
- 12. (Currently Amended) A method of cleaning a substrate comprising:
 providing an aqueous sulfuric acid solution diluted by deionized water in a bath;
 immersing the substrate into the diluted aqueous sulfuric acid solution; and
 cleaning contaminants on the substrate in accordance with a reaction between the diluted
 aqueous sulfuric acid solution and the contaminants by applying a mega-sonic energy to the
 substrate including immersed in the diluted aqueous sulfuric acid solution.
- 13. (Original) The method of claim 12, wherein the diluted aqueous sulfuric acid solution comprises the deionized water and sulfuric acid by a volume ratio of about 500: 1 to about 8,000: 1.
- 14. (Original) The method of claim 12, wherein the sulfuric acid has a concentration of about 10 ppm to about 1,000 ppm.